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TITLE : EPOXY RESIN COMPOSITION AND BONDING USING IT

ABSTRACT : PURPOSE: To make it possible to coat at elevated temp. and to improve adhesiveness and resistance to shower after coating by compounding a liq. epoxy resin, a phenoxy resin, and fine powder of a blocked isocyanate and/or dicyandiamide.

CONSTITUTION: 100 pts.wt. epoxy resin (a) with a viscosity (at 25°C) of 10-50,000cps, an epoxy equivalent of 100-500, 1.5 or more epoxy groups on average in the molecular and being liq. at ordinary temp. (e.g. bisphenol A type epoxy resin), 10-50 pts.wt. phenoxy resin (b) with an average MW of 10,000-100,000 obtd. by reacting bisphenol A with epichlorohydrin, a curing agent (c) consisting of fine powder of a blocked isocyanate and/or dicyandiamide and, if necessary, a curing accelerator, filler, etc., are compounded together to obtain the title compsn. with a viscosity of 2,000-20,000P at 50°C and 500P or smaller at 100°C and with which an object can be continuously coated by heating it at 80-100°C. After the objects are heat-coated with this compsn., they are jointed and adhered together by heat-curing.

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